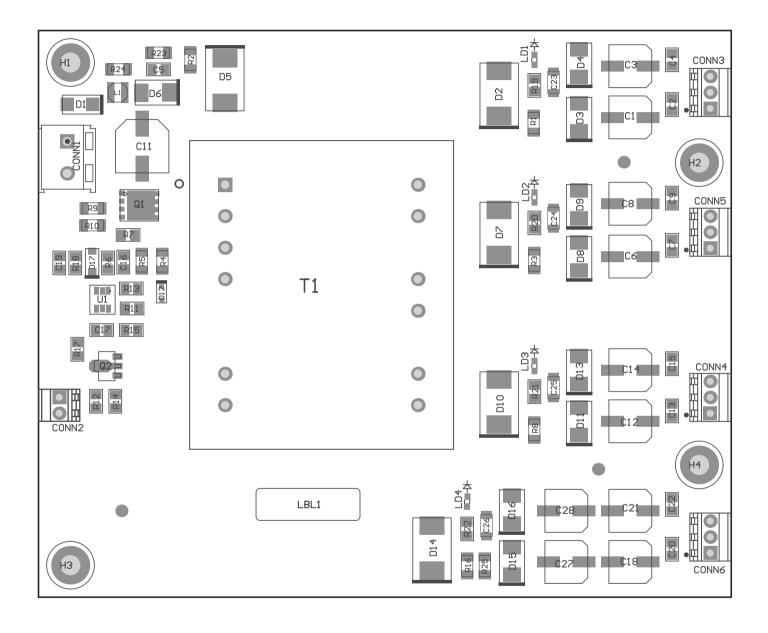
- ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00182	REV: E2	SUN REU	: Not In VersionControl
IGNORE ->				
PLOT NAME = Top Assembly Drawing	GENERATED : 7/1/20	14 3: 02: 39	PM	TEXAS INSTRUMENTS

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